

Silver Sintering For Power Electronics Meptec Org

Innovations in Nanoscience and Nanotechnology summarizes the state of the art in nano-sized materials. The authors focus on innovation aspects and highlight potentials for future developments and applications in health care, including pharmaceuticals, dentistry, and cosmetics; information and communications; energy; and chemical engineering. The chapters are written by leading researchers in nanoscience, chemistry, pharmacy, biology, chemistry, physics, engineering, medicine, and social science. The authors come from a range of backgrounds including academia, industry, and national and international laboratories around the world. This book is ideally suited for researchers and students in chemistry, physics, biology, engineering, materials science, and medicine and is a useful guide for industrialists. It aims to provide inspiration for scientists, new ideas for developers and innovators in industry, and guidelines for toxicologists. It also provides guidelines for agencies and government authorities to establish safe working conditions.

Hybrid energy systems integrate multiple sources of power generation, storage, and transport mechanisms and can facilitate increased usage of cleaner, renewable, and more efficient energy sources. Hybrid Power: Generation, Storage, and Grids discusses hybrid energy systems from fundamentals through applications and discusses generation, storage, and grids. Highlights fundamentals and applications of hybrid energy storage Discusses use in hybrid and electric vehicles and home energy needs Discusses issues related to hybrid renewable energy systems connected to the utility grid Describes the usefulness of hybrid microgrids and various forms of off-grid energy such as mini-grids, nanogrids, and stand-alone systems Covers the use of hybrid renewable energy systems for rural electrification around the world Discusses various forms and applications of hybrid energy systems, hybrid energy storage, hybrid microgrids, and hybrid off-grid energy systems Details simulation and optimization of hybrid renewable energy systems This book is aimed at advanced students and researchers in academia, government, and industry, seeking a comprehensive overview of the basics, technologies, and applications of hybrid energy systems.

Electromagnetic field-assisted sintering techniques have increasingly attracted attention of scientists and technologists. Spark-plasma sintering (SPS) and other field-assisted powder consolidation approaches provide remarkable capabilities to the processing of materials into configurations previously unattainable. Of particular significance is the possibility of using very fast heating rates, which, coupled with the field-assisted mass transport, stand behind the purported ability to achieve high densities during consolidation and to maintain the nanostructure of consolidated materials via these techniques. Potentially, SPS and related technologies have many significant advantages over the conventional powder processing methods, including the lower process temperature, the shorter holding time, dramatically improved properties

of sintered products, low manufacturing costs, and environmental friendliness.

The book presents interesting topics from the area of modeling and simulation of electric vehicles application. The results presented by the authors of the book chapters are very interesting and inspiring. The book will familiarize the readers with the solutions and enable the readers to enlarge them by their own research. It will be useful for students of Electrical Engineering; it helps them solve practical problems.

Modeling, Analysis, Design and Testing for Electronics Packaging Beyond Moore provides an overview of electrical, thermal and thermomechanical modeling, analysis, design and testing for 2.5D/3D. The book addresses important topics, including electrically and thermally induced issues, such as EMI and thermal issues, which are crucial to package signal and thermal integrity. It also covers modeling methods to address thermomechanical stress related to the package structural integrity. In addition, practical design and test techniques for packages and systems are included. Includes advanced modeling and analysis methods and techniques for state-of-the art electronics packaging Features experimental characterization and qualifications for the analysis and verification of electronic packaging design Provides multiphysics modeling and analysis techniques of electronic packaging

This book presents a liber amicorum dedicated to Wolfgang H. Müller, and highlights recent advances in Prof. Müller's major fields of research: continuum mechanics, generalized mechanics, thermodynamics, mechanochemistry, and geomechanics. Over 50 of Prof. Müller's friends and colleagues contributed to this book, which commemorates his 60th birthday and was published in recognition of his outstanding contributions.

SiC and GaN devices have been around for some time. The first dedicated international conference on SiC and related devices, "ICSCRM," was held in Washington, DC, in 1987. But only recently, the commercialization of SiC and GaN devices has happened. Due to its material properties, Si as a semiconductor has limitations in high-temperature, high-voltage, and high-frequency regimes. With the help of SiC and GaN devices, it is possible to realize more efficient power systems. Devices manufactured from SiC and GaN have already been impacting different areas with their ability to outperform Si devices. Some of the examples are the telecommunications, automotive/locomotive, power, and renewable energy industries. To achieve the carbon emission targets set by different countries, it is inevitable to use these new technologies. This book attempts to cover all the important facets related to wide bandgap semiconductor technology, including new challenges posed by it. This book is intended for graduate students, researchers, engineers, and technology experts who have been working in the exciting fields of SiC and GaN power devices.

The Proceedings of the 11th European Conference on Thermoelectrics contains manuscripts from leading experts on topics spanning from material processing to applications in the field of thermoelectrics. The selected manuscripts also

describe recent developments on measurement systems of thermoelectric properties, and the design and modelling of thermoelectric generators.

Die-Attach Materials for High Temperature Applications in Microelectronics Packaging Materials, Processes, Equipment, and Reliability Springer

This book is a printed edition of the Special Issue "Interface Circuits for Microsensor Integrated Systems" that was published in Micromachines

The development of electronics that can operate at high temperatures has been identified as a critical technology for the next century. Increasingly, engineers will be called upon to design avionics, automotive, and geophysical electronic systems requiring components and packaging reliable to 200 °C and beyond. Until now, however, they have had no single resource on high temperature electronics to assist them. Such a resource is critically needed, since the design and manufacture of electronic components have now made it possible to design electronic systems that will operate reliably above the traditional temperature limit of 125 °C. However, successful system development efforts hinge on a firm understanding of the fundamentals of semiconductor physics and device processing, materials selection, package design, and thermal management, together with a knowledge of the intended application environments. High Temperature Electronics brings together this essential information and presents it for the first time in a unified way. Packaging and device engineers and technologists will find this book required reading for its coverage of the techniques and tradeoffs involved in materials selection, design, and thermal management and for its presentation of best design practices using actual fielded systems as examples. In addition, professors and students will find this book suitable for graduate-level courses because of its detailed level of explanation and its coverage of fundamental scientific concepts. Experts from the field of high temperature electronics have contributed to nine chapters covering topics ranging from semiconductor device selection to testing and final assembly.

EPTC 2019 will feature keynotes, technical sessions, short courses, forums, exhibitions, social and networking activities It aims to provide a good coverage of technology developments in all areas of electronics packaging from design to manufacturing and operation It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in the Asia Pacific and is well attended by experts in all aspects of packaging technology from all over the world EPTC is the flagship conference of IEEE EPS in Region 10

Based on the sintering conference held at the Pennsylvania State University, USA, this text presents advances in the application of sintering to the most important industrial materials. It offers results on both solid-state and microphase sintering as well as microstructure evolution, and introduces new applications, processes, materials and solutions to technical problems.

This book reports on cutting-edge design methods and tools in industrial engineering, advanced findings in mechanics and material science, and relevant technological applications. Topics span from geometric modelling tools to applications of virtual/augmented reality, from interactive design to ergonomics, human factors research and reverse engineering. Further topics include integrated design and optimization methods, as well as experimental validation techniques for product, processes and systems development, such as additive manufacturing technologies. This book is based on the International Conference on Design Tools and Methods in Industrial Engineering, ADM 2019, held on September 9–10, 2019, in Modena, Italy, and organized by the Italian Association of Design Methods and Tools for Industrial Engineering,

and the Department of Engineering “Enzo Ferrari” of the University of Modena and Reggio Emilia, Italy. It provides academics and professionals with a timely overview and extensive information on trends and technologies in industrial design and manufacturing. This book analyzes the thermal characteristics of power electronic devices (PEDs) with a focus on those used in wind and solar energy systems. The authors focus on the devices used in such applications, for example boost converters and inverters under different operating conditions. The book explains in detail finite element modeling techniques, setting up measuring systems, data analysis, and PEDs’ lifetime calculations. It is appropriate reading for graduate students and researchers who focus on the design and reliability of power electronic devices.

Semiconductor nanocrystals and metal nanoparticles are the building blocks of the next generation of electronic, optoelectronic, and photonic devices. Covering this rapidly developing and interdisciplinary field, the book examines in detail the physical properties and device applications of semiconductor nanocrystals and metal nanoparticles. It begins with a review of the synthesis and characterization of various semiconductor nanocrystals and metal nanoparticles and goes on to discuss in detail their optical, light emission, and electrical properties. It then illustrates some exciting applications of nanoelectronic devices (memristors and single-electron devices) and optoelectronic devices (UV detectors, quantum dot lasers, and solar cells), as well as other applications (gas sensors and metallic nanopastes for power electronics packaging). Focuses on a new class of materials that exhibit fascinating physical properties and have many exciting device applications. Presents an overview of synthesis strategies and characterization techniques for various semiconductor nanocrystal and metal nanoparticles. Examines in detail the optical/optoelectronic properties, light emission properties, and electrical properties of semiconductor nanocrystals and metal nanoparticles. Reviews applications in nanoelectronic devices, optoelectronic devices, and photonic devices.

EPTC 2018 will feature keynotes, technical sessions, short courses, forums, an exhibition, social and networking activities It aims to provide a good coverage of technology developments in all areas of electronics packaging from design to manufacturing and operation It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts This year, to commemorate the 20th anniversary of EPTC, one extra day of special events will be added to the conference program Advances in Nanotechnology Research and Application / 2012 Edition is a ScholarlyEditions™ eBook that delivers timely, authoritative, and comprehensive information about Nanotechnology. The editors have built Advances in Nanotechnology Research and Application / 2012 Edition on the vast information databases of ScholarlyNews.™ You can expect the information about Nanotechnology in this eBook to be deeper than what you can access anywhere else, as well as consistently reliable, authoritative, informed, and relevant. The content of Advances in Nanotechnology Research and Application / 2012 Edition has been produced by the world’s leading scientists, engineers, analysts, research institutions, and companies. All of the content is from peer-reviewed sources, and all of it is written, assembled, and edited by the editors at ScholarlyEditions™ and available exclusively from us. You now have a source you can cite with authority, confidence, and credibility. More information is available at <http://www.ScholarlyEditions.com/>.

Emerging wide bandgap (WBG) semiconductors hold the potential to advance the global industry in the same way that, more than 50 years ago, the invention of the silicon (Si) chip enabled the modern computer era. SiC- and GaN-based devices are starting to

become more commercially available. Smaller, faster, and more efficient than their counterpart Si-based components, these WBG devices also offer greater expected reliability in tougher operating conditions. Furthermore, in this frame, a new class of microelectronic-grade semiconducting materials that have an even larger bandgap than the previously established wide bandgap semiconductors, such as GaN and SiC, have been created, and are thus referred to as “ultra-wide bandgap” materials. These materials, which include AlGa_N, AlN, diamond, Ga₂O₃, and BN, offer theoretically superior properties, including a higher critical breakdown field, higher temperature operation, and potentially higher radiation tolerance. These attributes, in turn, make it possible to use revolutionary new devices for extreme environments, such as high-efficiency power transistors, because of the improved Baliga figure of merit, ultra-high voltage pulsed power switches, high-efficiency UV-LEDs, and electronics. This Special Issue aims to collect high quality research papers, short communications, and review articles that focus on wide bandgap device design, fabrication, and advanced characterization. The Special Issue will also publish selected papers from the 43rd Workshop on Compound Semiconductor Devices and Integrated Circuits, held in France (WOCSDICE 2019), which brings together scientists and engineers working in the area of III–V, and other compound semiconductor devices and integrated circuits. In particular, the following topics are addressed: – GaN- and SiC-based devices for power and optoelectronic applications – Ga₂O₃ substrate development, and Ga₂O₃ thin film growth, doping, and devices – AlN-based emerging material and devices – BN epitaxial growth, characterization, and devices

Designing and building power semiconductor modules requires a broad, interdisciplinary base of knowledge and experience, ranging from semiconductor materials and technologies, thermal management, and soldering to environmental constraints, inspection techniques, and statistical process control. This diversity poses a significant challenge to engine

Power Electronic Packaging presents an in-depth overview of power electronic packaging design, assembly, reliability and modeling. Since there is a drastic difference between IC fabrication and power electronic packaging, the book systematically introduces typical power electronic packaging design, assembly, reliability and failure analysis and material selection so readers can clearly understand each task's unique characteristics. Power electronic packaging is one of the fastest growing segments in the power electronic industry, due to the rapid growth of power integrated circuit (IC) fabrication, especially for applications like portable, consumer, home, computing and automotive electronics. This book also covers how advances in both semiconductor content and power advanced package design have helped cause advances in power device capability in recent years. The author extrapolates the most recent trends in the book's areas of focus to highlight where further improvement in materials and techniques can drive continued advancements, particularly in thermal management, usability, efficiency, reliability and overall cost of power semiconductor solutions.

Sustainable development is a globally recognized mandate and it includes green or environment-friendly manufacturing practices. Such practices orchestrate with the self-healing and self-replenishing capability of natural ecosystems. Green manufacturing encompasses synthesis, processing, fabrication, and process optimization, but also testing, performance evaluation and reliability.

The book shall serve as a comprehensive and authoritative resource on sustainable manufacturing of ceramics, metals and their composites. It is designed to capture the diversity and unity of methods and approaches to materials processing, manufacturing, testing and evaluation across disciplines and length scales. Each chapter incorporates in-depth technical information without compromising the delicate link between factual data and fundamental concepts or between theory and practice. Green and sustainable materials processing and manufacturing is designed as a key enabler of sustainable development. A one-stop compendium of new research and technology of green manufacturing of metals, ceramics and their composites In-depth cutting-edge treatment of synthesis, processing, fabrication, process optimization, testing, performance evaluation and reliability which are of critical importance to green manufacturing Stimulates fresh thinking and exchange of ideas and information on approaches to green materials processing across disciplines

Sintering is the process of forming materials and components from a powder under the action of thermal energy. It is a key materials science subject: most ceramic materials and many specialist metal powder products for use in key industries such as electronics, automotive and aerospace are formed this way. Written by one of the leading experts in the field, this book offers an unrivalled introduction to sintering and sintering processes for students of materials science and engineering, and practicing engineers in industry. The book is unique in providing a complete grounding in the principles of sintering and equal coverage of the three key sintering processes: densification, grain growth and microstructure. Students and professional engineers alike will be attracted by the emphasis on developing a detailed understanding of the theory and practical processes of sintering, the balanced coverage of ceramic and metal sintering, and the accompanying examination questions with selected solutions. Delivering unrivalled depth of coverage on the basis of sintering, science, including thermodynamics and polycrystalline microstructure. Unique in its balanced coverage of the three key sintering elements - densification, grain growth and microstructure. A key reference for students and engineers in materials science and engineering, accompanied by examination questions and selected solutions.

Examines the advantages of Embedded and FO-WLP technologies, potential application spaces, package structures available in the industry, process flows, and material challenges Embedded and fan-out wafer level packaging (FO-WLP) technologies have been developed across the industry over the past 15 years and have been in high volume manufacturing for nearly a decade. This book covers the advances that have been made in this new packaging technology and discusses the many benefits it provides to the electronic packaging industry and supply chain. It provides a compact overview of the major types of technologies offered in this field, on what is available, how it is processed, what is driving its development, and the pros and cons. Filled with contributions from some of the field's leading experts, Advances in Embedded and Fan-Out Wafer Level Packaging Technologies begins with a look at the history of the technology. It then goes on to examine the biggest technology and marketing trends. Other sections are dedicated to chip-first FO-WLP, chip-last FO-WLP, embedded die packaging, materials challenges, equipment challenges, and resulting technology fusions. Discusses specific company standards and their development results Content relates to practice as

well as to contemporary and future challenges in electronics system integration and packaging Advances in Embedded and Fan-Out Wafer Level Packaging Technologies will appeal to microelectronic packaging engineers, managers, and decision makers working in OEMs, IDMs, IFMs, OSATs, silicon foundries, materials suppliers, equipment suppliers, and CAD tool suppliers. It is also an excellent book for professors and graduate students working in microelectronic packaging research.

Power Electronics Basics: Operating Principles, Design, Formulas, and Applications provides fundamental knowledge for the analysis and design of modern power electronic devices. This concise and user-friendly resource: Explains the basic concepts and most important terms of power electronics Describes the power assemblies, control, and passive components of semiconductor power switches Covers the control of power electronic devices, from mathematical modeling to the analysis of the electrical processes Addresses pulse-width modulation, power quality control, and multilevel, modular, and multicell power converter topologies Discusses line-commutated and resonant converters, as well as inverters and AC converters based on completely controllable switches Explores cutting-edge applications of power electronics, including renewable energy production and storage, fuel cells, and electric drives Power Electronics Basics: Operating Principles, Design, Formulas, and Applications supplies graduate students, industry professionals, researchers, and academics with a solid understanding of the underlying theory, while offering an overview of the latest achievements and development prospects in the power electronics industry.

This collection presents papers from the 149th Annual Meeting & Exhibition of The Minerals, Metals & Materials Society.

This book presents selected papers from the 5th International Conference on Mechanical, Manufacturing and Plant Engineering (ICMMPE 2019), held in Kuala Lumpur, Malaysia. It highlights the latest advances in the area, brings together researchers and professionals in the field and provides a valuable platform for exchanging ideas and fostering collaboration. Joining technologies could be change to manufacturing technologies. Addressing real-world problems concerning joining technologies that are at the heart of various manufacturing sectors, the respective papers present the outcomes of the latest experimental and numerical work on problems in soldering, arc welding and solid-state joining technologies. technologies.

This volume collects selected papers of the 5th CESA Automotive Electronics Congress, Paris, 2018. CESA is the most important automotive electronics conference in France. The topical focus lies on state-of-the-art automotive electronics with respect to energy consumption and autonomous driving. The target audience primarily comprises industry leaders and research experts in the automotive industry.

This report summarizes a study where various properties of bulk-sintered silver were investigated over a range of porosity. This work was conducted within the National Transportation Research Center's Power Device Packaging project that is part of the DOE Vehicle Technologies Advanced Power Electronics and Electric Motors Program. Sintered silver, as an interconnect material in power electronics, inherently has porosity in its produced structure because of the way it is made. Therefore, interest existed in this study to examine if that porosity affected electrical properties, thermal properties, and mechanical properties because any dependencies could affect the intended function (e.g., thermal transfer, mechanical stress relief, etc.) or reliability of that interconnect layer and alter how its performance is modeled. Disks of bulk-sintered silver were fabricated using different starting silver pastes and different sintering conditions to promote different amounts of porosity. Test coupons were harvested out of the disks to measure electrical resistivity and electrical conductivity, thermal conductivity, coefficient of thermal expansion, elastic modulus, Poisson's ratio, and yield stress. The authors fully recognize that the

microstructure of processed bulk silver coupons may indeed not be identical to the microstructure produced in thin (20-50 microns) layers of sintered silver. However, measuring these same properties with such a thin actual structure is very difficult, requires very specialized specimen preparation and unique testing instrumentation, is expensive, and has experimental shortfalls of its own, so the authors concluded that the herein measured responses using processed bulk sintered silver coupons would be sufficient to determine acceptable values of those properties. Almost all the investigated properties of bulk sintered silver changed with porosity content within a range of 3-38% porosity. Electrical resistivity, electrical conductivity, thermal conductivity, elastic modulus, Poisson's ratio, and yield stress all depended on the porosity content in bulk-sintered silver. The only investigated property that was independent of porosity in that range was coefficient of thermal expansion.

Provides in-depth knowledge on novel materials that make electronics work under high-temperature and high-pressure conditions This book reviews the state of the art in research and development of lead-free interconnect materials for electronic packaging technology. It identifies the technical barriers to the development and manufacture of high-temperature interconnect materials to investigate into the complexities introduced by harsh conditions. It teaches the techniques adopted and the possible alternatives of interconnect materials to cope with the impacts of extreme temperatures for implementing at industrial scale. The book also examines the application of nanomaterials, current trends within the topic area, and the potential environmental impacts of material usage. Written by world-renowned experts from academia and industry, Harsh Environment Electronics: Interconnect Materials and Performance Assessment covers interconnect materials based on silver, gold, and zinc alloys as well as advanced approaches utilizing polymers and nanomaterials in the first section. The second part is devoted to the performance assessment of the different interconnect materials and their respective environmental impact. -Takes a scientific approach to analyzing and addressing the issues related to interconnect materials involved in high temperature electronics -Reviews all relevant materials used in interconnect technology as well as alternative approaches otherwise neglected in other literature -Highlights emergent research and theoretical concepts in the implementation of different materials in soldering and die-attach applications -Covers wide-bandgap semiconductor device technologies for high temperature and harsh environment applications, transient liquid phase bonding, glass frit based die attach solution for harsh environment, and more -A pivotal reference for professionals, engineers, students, and researchers Harsh Environment Electronics: Interconnect Materials and Performance Assessment is aimed at materials scientists, electrical engineers, and semiconductor physicists, and treats this specialized topic with breadth and depth.

This book serves as an invaluable reference to Power Electronics Design, covering the application of high-power semiconductor technology to large motor drives, power supplies, power conversion equipment, electric utility auxiliaries and numerous other applications. Design engineers, design drafters and technicians in the power electronics industry, as well as students studying power electronics in various contexts, will benefit from Keith Sueker's decades of experience in the industry. With this experience, the author has put the overall power electronics design process in the context of primary electronic components and the many associated components required for a system. The seeming complexity of power electronics design is made transparent with Keith Sueker's simple, direct language and a minimum reliance on mathematics. Readers will come away with a wealth of practical design information that has hundreds of explanatory diagrams to support it, having also seen many examples of potential pitfalls in the design process. * A down-to-earth approach, free of complex jargon and esoteric information. * Over 200 illustrations to clarify discussion points. * Examples of costly design goofs will provide invaluable cautionary advice. This book is about solders and their composition and focuses on material characterizations and the methods used to make alloys and

determine their structures, physical properties and applications. Physical properties and the factors that control them and theoretical verification are the main contents of this book. Corrosion of solders is included in the coverage of the properties related to solder composition and mechanical properties.

Avoiding Inelastic Strains in Solder Joint Interconnections of IC Devices addresses analytical (mathematical) modeling approaches aimed at understanding the underlying physics and mechanics of the behavior and performance of solder materials and solder joint interconnections of IC devices. The emphasis is on design for reliability, including probabilistic predictions of the solder lifetime. Describes how to use the developed methods of analytical predictive modeling to minimize thermal stresses and strains in solder joint of IC devices Shows how to build the preprocessing models in finite-element analyses (FEA) by comparing the FEA and analytical data Covers how to design the most effective test vehicles for testing solder joints Details how to design and organize, in addition to or sometimes even instead of highly accelerated life tests (HALT), highly focused and highly cost-effective failure oriented accelerated testing (FOAT) to understand the physic of failure of solder joint interconnections Outlines how to convert the low cycle fatigue conditions into elastic fatigue conditions and to assess the fatigue lifetime in such cases Illustrates ways to replace time- and labor-consuming, expensive, and possibly misleading temperature cycling tests with simpler and physically meaningful accelerated tests This book is aimed towards professionals in electronic and photonic packaging, electronic and optical materials, materials engineering, and mechanical design.

This book relates the recent developments in several key electrical engineering R&D labs, concentrating on power electronics switches and their use. The first sections deal with key power electronics technologies, MOSFETs and IGBTs, including series and parallel associations. The next section examines silicon carbide and its potentiality for power electronics applications and its present limitations. Then, a dedicated section presents the capacitors, key passive components in power electronics, followed by a modeling method allowing the stray inductances computation, necessary for the precise simulation of switching waveforms. Thermal behavior associated with power switches follows, and the last part proposes some interesting prospectives associated to Power Electronics integration.

A guide to the field of wide bandgap semiconductor technology Wide Bandgap Semiconductors for Power Electronics is a comprehensive and authoritative guide to wide bandgap materials silicon carbide, gallium nitride, diamond and gallium(III) oxide. With contributions from an international panel of experts, the book offers detailed coverage to the growth of these materials, their characterization, and how they are used in a variety of power electronics devices such as transistors and diodes and in the areas of quantum information and hybrid electric vehicles. The book is filled with the most recent developments in the burgeoning field of wide bandgap semiconductor technology and includes information from cutting-edge semiconductor companies as well as material from leading universities and research institutions. By taking both scholarly and industrial perspectives, the book is designed to be a useful resource for scientists, academics, and corporate researchers and developers. This important book: Presents a review of wide bandgap materials and recent developments Links the high potential of the wide bandgap semiconductor with the technologic

implementation capabilities Offers a unique combination academic and industrial perspectives Meets the demand for a resource that addresses wide bandgap materials in a comprehensive manner Written for materials scientists, semiconductor physicists, electrical engineers, Wide Bandgap Semiconductors for Power Electronics provides a state of the art guide to the technology and application of SiC and related wide bandgap materials.

This book presents the scientific principles, processing conditions, probable failure mechanisms, and a description of reliability performance and equipment required for implementing high-temperature and lead-free die attach materials. In particular, it addresses the use of solder alloys, silver and copper sintering, and transient liquid-phase sintering. While different solder alloys have been used widely in the microelectronics industry, the implementation of sintering silver and transient liquid-phase sintering remains limited to a handful of companies. Hence, the book devotes many chapters to sintering technologies, while simultaneously providing only a cursory coverage of the more widespread techniques employing solder alloys. Addresses the differences between sintering and soldering (the current die-attach technologies), thereby comprehensively addressing principles, methods, and performance of these high-temperature die-attach materials; Emphasizes the industrial perspective, with chapters written by engineers who have hands-on experience using these technologies; Baker Hughes, Bosch and ON Semiconductor, are represented as well as materials suppliers such as Indium; Simultaneously provides the detailed science underlying these technologies by leading academic researchers in the field.

Unfriendly to conventional electronic devices, circuits, and systems, extreme environments represent a serious challenge to designers and mission architects. The first truly comprehensive guide to this specialized field, Extreme Environment Electronics explains the essential aspects of designing and using devices, circuits, and electronic systems intended to operate in extreme environments, including across wide temperature ranges and in radiation-intense scenarios such as space. The Definitive Guide to Extreme Environment Electronics Featuring contributions by some of the world's foremost experts in extreme environment electronics, the book provides in-depth information on a wide array of topics. It begins by describing the extreme conditions and then delves into a description of suitable semiconductor technologies and the modeling of devices within those technologies. It also discusses reliability issues and failure mechanisms that readers need to be aware of, as well as best practices for the design of these electronics. Continuing beyond just the "paper design" of building blocks, the book rounds out coverage of the design realization process with verification techniques and chapters on electronic packaging for extreme environments. The final set of chapters describes actual chip-level designs for applications in energy and space exploration. Requiring only a basic background in electronics, the book combines theoretical and practical aspects in each self-contained chapter. Appendices supply additional background material. With its broad coverage and depth, and the expertise of the contributing authors, this is an invaluable reference for engineers, scientists, and technical managers, as well as researchers and graduate students. A hands-on resource, it explores what is required to successfully operate electronics in the most demanding conditions.

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